

# MECHANICAL CASE OUTLINE

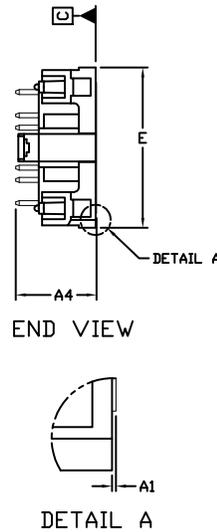
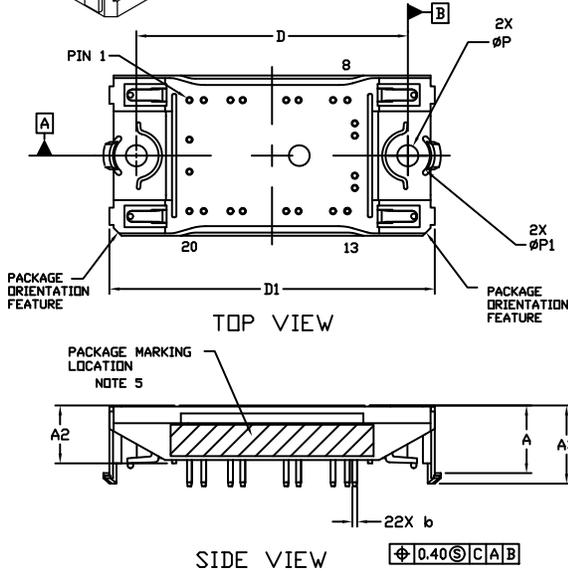
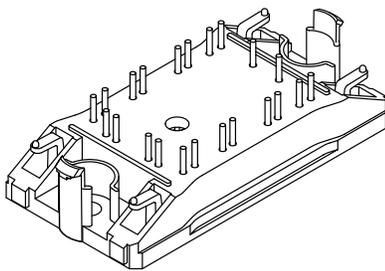
## PACKAGE DIMENSIONS

ON Semiconductor®



### PIM22, 55x32.5 / Q0BOOST CASE 180AJ ISSUE B

DATE 08 NOV 2017



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO THE PLATED TERMINALS AND IS MEASURED BETWEEN 1.00 AND 3.00 FROM THE TERMINAL TIP.
4. POSITION OF THE CENTER OF THE TERMINALS IS DETERMINED FROM DATUM B THE CENTER OF DIMENSION D, X DIRECTION, AND FROM DATUM A, Y DIRECTION. POSITIONAL TOLERANCE, AS NOTED IN DRAWING, APPLIES TO EACH TERMINAL IN BOTH DIRECTIONS.
5. PACKAGE MARKING IS LOCATED AS SHOWN ON THE SIDE OPPOSITE THE PACKAGE ORIENTATION FEATURES.

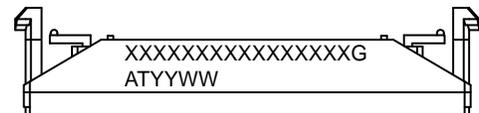
DIM	MILLIMETERS	
	MIN.	NDM.
A	13.50	13.90
A1	0.10	0.30
A2	11.50	11.90
A3	15.65	16.05
A4	16.35 REF	
b	0.95	1.05
D	54.80	55.20
D1	65.60	66.20
E	32.20	32.80
P	4.20	4.40
P1	8.90	9.10

**MOUNTING HOLE POSITION**

NOTE 4

PIN	HOLE POSITION		PIN	PIN POSITION		PIN	PIN POSITION		PIN	PIN POSITION	
	X	Y		X	Y		X	Y		X	Y
1	-16.75	-11.25	12	16.75	6.55	1	-16.75	11.25	12	16.75	-6.55
2	-13.85	-11.25	13	15.25	11.25	2	-13.85	11.25	13	15.25	-11.25
3	-8.45	-11.25	14	12.35	11.25	3	-8.45	11.25	14	12.35	-11.25
4	-5.95	-11.25	15	5.35	11.25	4	-5.95	11.25	15	5.35	-11.25
5	2.85	-11.25	16	2.85	11.25	5	2.85	11.25	16	2.85	-11.25
6	5.35	-11.25	17	-5.95	11.25	6	5.35	11.25	17	-5.95	-11.25
7	12.35	-11.25	18	-8.45	11.25	7	12.35	11.25	18	-8.45	-11.25
8	15.25	-11.25	19	-13.85	11.25	8	15.25	11.25	19	-13.85	-11.25
9	16.75	-6.55	20	-16.75	11.25	9	16.75	6.55	20	-16.75	-11.25
10	16.75	-4.05	21	-16.75	3.25	10	16.75	4.05	21	-16.75	-3.25
11	16.75	4.05	22	-16.75	-3.25	11	16.75	-4.05	22	-16.75	3.25

**GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code  
 G = Pb-Free Package  
 AT = Assembly & Test Site Code  
 YYWW = Year and Work Week Code

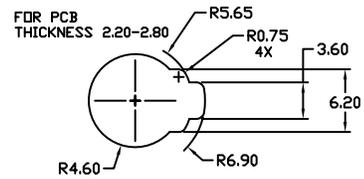
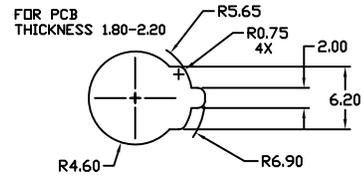
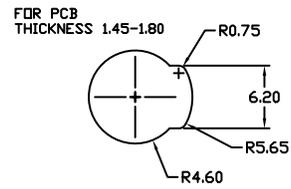
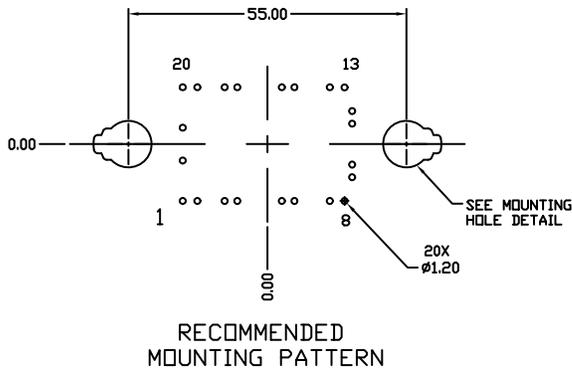
\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

**MOUNTING FOOTPRINT ON PAGE 2**

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>PIM22 55X32.5 / Q0BOOST (SOLDER PIN)</b>	<b>PAGE 1 OF 3</b>

PIM22, 55x32.5 / Q0BOOST  
CASE 180AJ  
ISSUE B

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MOUNTING HOLE DETAIL

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